

## Description

### PECJ N-channel Enhancement Mode Power MOSFET

#### Features

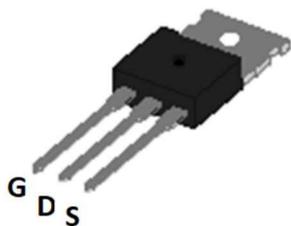
- 68V, 80A  
 $R_{DS(ON)} < 9m\Omega @ V_{GS} = 10V$
- Advanced Trench Technology
- Provide Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

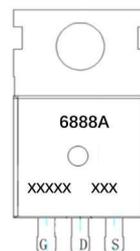
- Load Switch
- PWM Application
- Power management



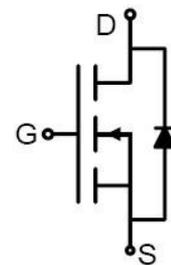
*100% UIS TESTED!*  
*100%  $\Delta V_{ds}$  TESTED!*



TO-220C top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

| Device Marking | Device    | OUTLINE | Device Package | TUBE (PCS) | Inner Box (PCS) | Per Carton (PCS) |
|----------------|-----------|---------|----------------|------------|-----------------|------------------|
| PECJ6888A      | PECJ6888A | TUBE    | TO-220C        | 50         | 1,000           | 8,000            |

## Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise specified)

| Symbol          | Parameter   | Max.                | Units        |
|-----------------|---|---------------------|--------------|
| $V_{DSS}$       | Drain-Source Voltage                                | 68                  | V            |
| $V_{GSS}$       | Gate-Source Voltage                                 | $\pm 20$            | V            |
| $I_D$           | Continuous Drain Current                            | $T_C = 25^\circ C$  | 80           |
|                 |   | $T_C = 100^\circ C$ | 52           |
| $I_{DM}$        | Pulsed Drain Current <small>note1</small>           | 320                 | A            |
| $E_{AS}$        | Single Pulsed Avalanche Energy <small>note2</small> | 110                 | mJ           |
| $P_D$           | Power Dissipation                                   | $T_C = 25^\circ C$  | 103          |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case                | 1.46                | $^\circ C/W$ |
| $T_J, T_{STG}$  | Operating and Storage Temperature Range             | -55 to +175         | $^\circ C$   |

## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

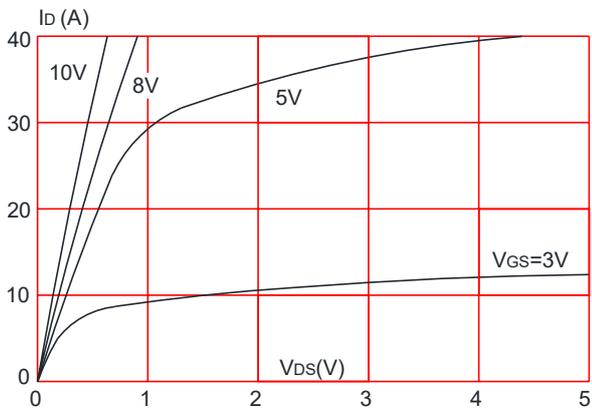
| Symbol  | Parameter   | Test Condition  | Min. | Typ. | Max. | Units |
|---|---|---|------|------|------|-------|
| <b>Off Characteristic</b>                                     |   |   |      |      |      |       |
| V <sub>(BR)DSS</sub>  | Drain-Source Breakdown Voltage                            | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA  | 68   | -    | -    | V     |
| I <sub>DSS</sub>  | Zero Gate Voltage Drain Current                           | V <sub>DS</sub> =68V, V <sub>GS</sub> =0V,  | -    | -    | 1.0  | μA    |
| I <sub>GSS</sub>  | Gate to Body Leakage Current                              | V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V  | -    | -    | ±100 | nA    |
| <b>On Characteristics</b>                                     |   |   |      |      |      |       |
| V <sub>GS(th)</sub>   | Gate Threshold Voltage                                    | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                    | 2    | 3    | 4    | V     |
| R <sub>DS(on)</sub>   | Static Drain-Source on-Resistance<br><small>note3</small> | V <sub>GS</sub> =10V, I <sub>D</sub> =30A   | -    | 7.5  | 9    | mΩ    |
| <b>Dynamic Characteristics</b>                                |   |   |      |      |      |       |
| C <sub>iss</sub>  | Input Capacitance   | V <sub>DS</sub> =30V, V <sub>GS</sub> =0V,<br>f=1.0MHz                                      | -    | 4000 | -    | pF    |
| C <sub>oss</sub>  | Output Capacitance  |   | -    | 267  | -    | pF    |
| C <sub>rss</sub>  | Reverse Transfer Capacitance                              |   | -    | 250  | -    | pF    |
| Q <sub>g</sub>  | Total Gate Charge   | V <sub>DS</sub> =30V, I <sub>D</sub> =30A,<br>V <sub>GS</sub> =10V                          | -    | 35   | -    | nC    |
| Q <sub>gs</sub>   | Gate-Source Charge  |   | -    | 10   | -    | nC    |
| Q <sub>gd</sub>   | Gate-Drain("Miller") Charge                               |   | -    | 9    | -    | nC    |
| <b>Switching Characteristics</b>                              |   |   |      |      |      |       |
| t <sub>d(on)</sub>  | Turn-on Delay Time  | V <sub>DS</sub> =30V,<br>I <sub>D</sub> =30A, R <sub>GEN</sub> =3Ω,<br>V <sub>GS</sub> =10V | -    | 15   | -    | ns    |
| t <sub>r</sub>  | Turn-on Rise Time   |   | -    | 90   | -    | ns    |
| t <sub>d(off)</sub>   | Turn-off Delay Time                                       |   | -    | 45   | -    | ns    |
| t <sub>f</sub>  | Turn-off Fall Time  |   | -    | 30   | -    | ns    |
| <b>Drain-Source Diode Characteristics and Maximum Ratings</b> |   |   |      |      |      |       |
| I <sub>S</sub>  | Maximum Continuous Drain to Source Diode Forward Current  |   | -    | -    | 80   | A     |
| I <sub>SM</sub>   | Maximum Pulsed Drain to Source Diode Forward Current      |   | -    | -    | 320  | A     |
| V <sub>SD</sub>   | Drain to Source Diode Forward Voltage                     | V <sub>GS</sub> =0V, I <sub>S</sub> =30A  | -    | -    | 1.2  | V     |
| t <sub>rr</sub>   | Body Diode Reverse Recovery Time                          | I <sub>F</sub> =20A, dI/dt=100A/μs  | -    | 78   | -    | ns    |
| Q <sub>rr</sub>   | Body Diode Reverse Recovery Charge                        |   | -    | 51   | -    | nC    |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

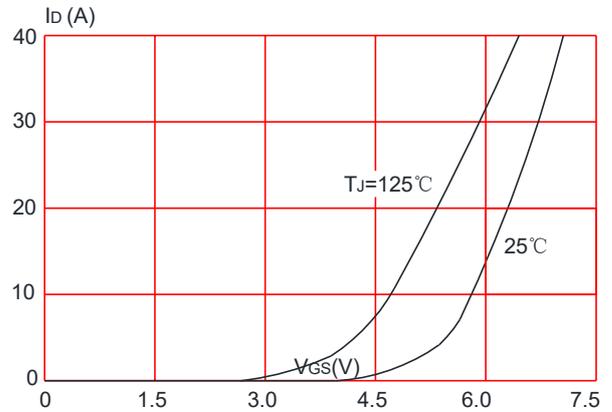
2. EAS condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=21A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

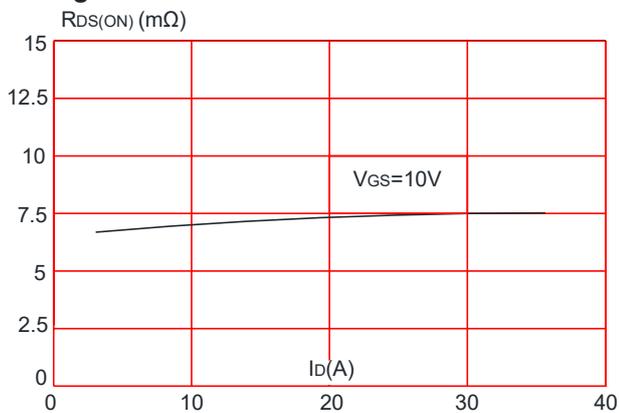
**Figure 1: Output Characteristics**



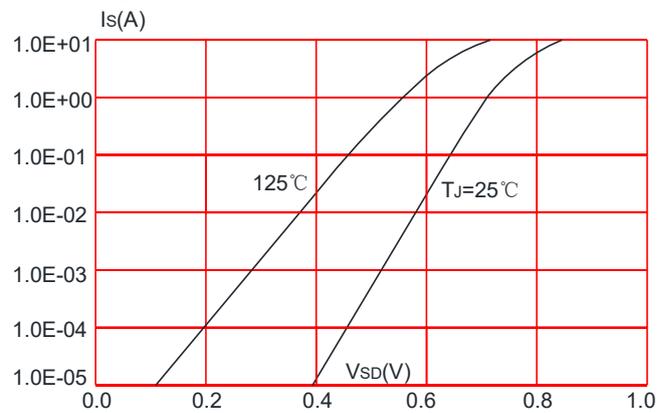
**Figure 2: Typical Transfer Characteristics**



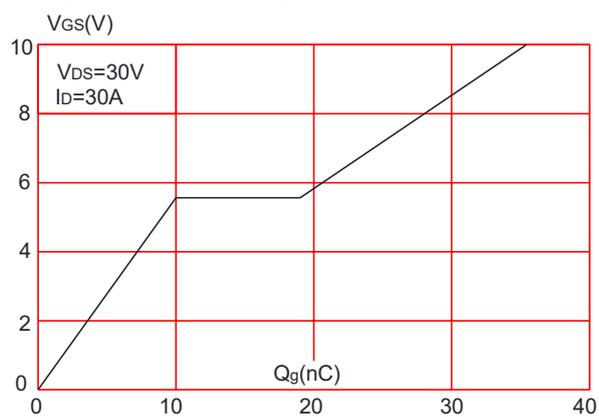
**Figure 3: On-resistance vs. Drain Current**



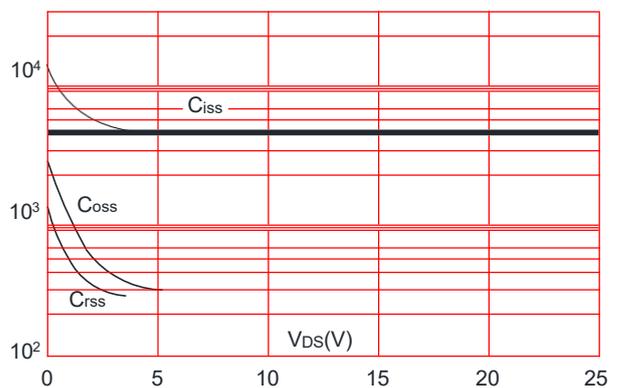
**Figure 4: Body Diode Characteristics**



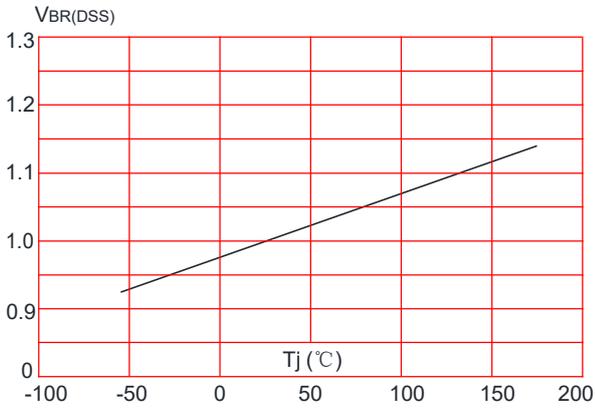
**Figure 5: Gate Charge Characteristics**



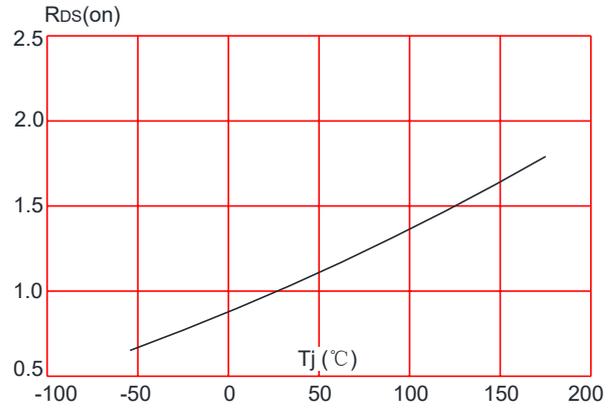
**Figure 6: Capacitance Characteristics**



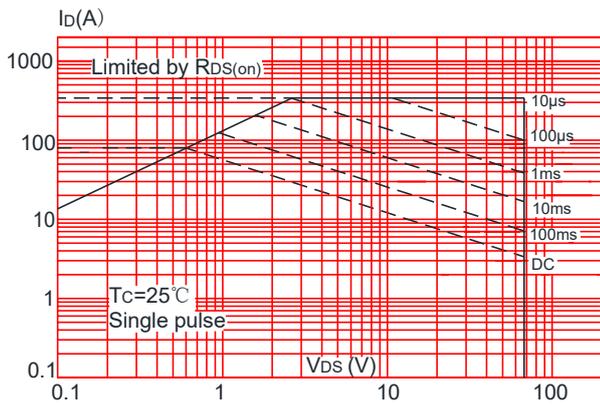
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



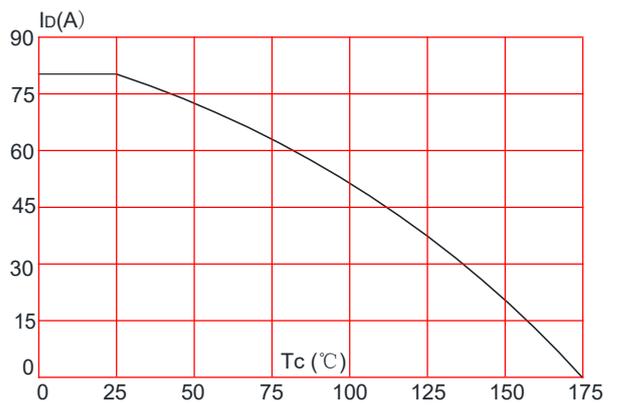
**Figure 8:** Normalized on Resistance vs. Junction Temperature



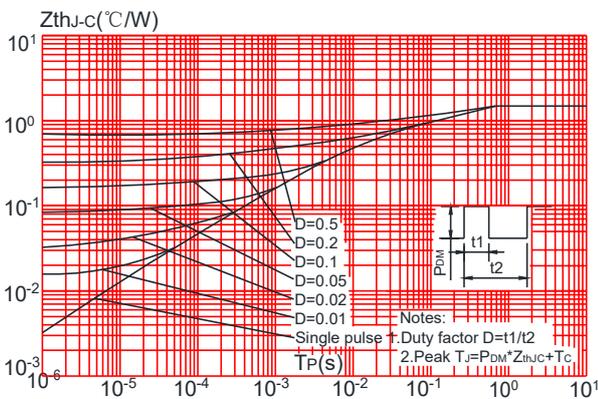
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



## Test Circuit

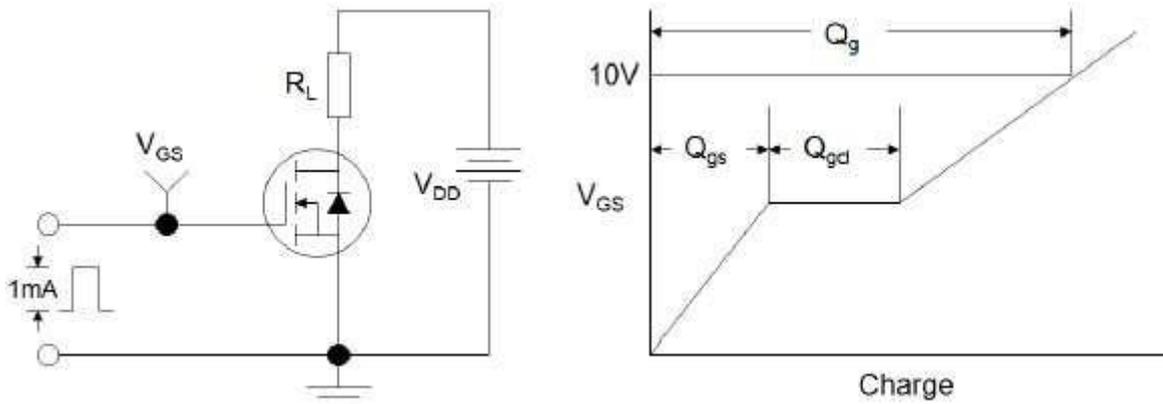


Figure1:Gate Charge Test Circuit & Waveform

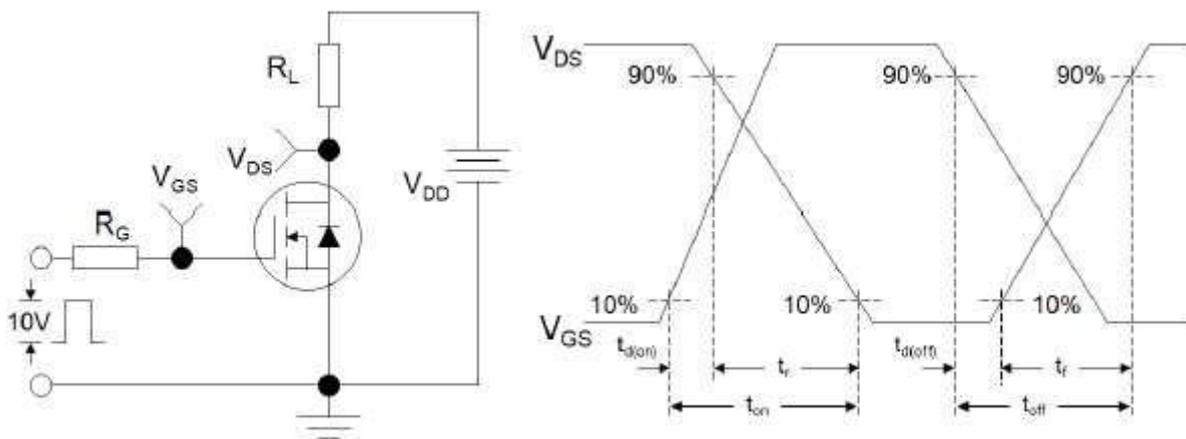


Figure 2: Resistive Switching Test Circuit & Waveforms

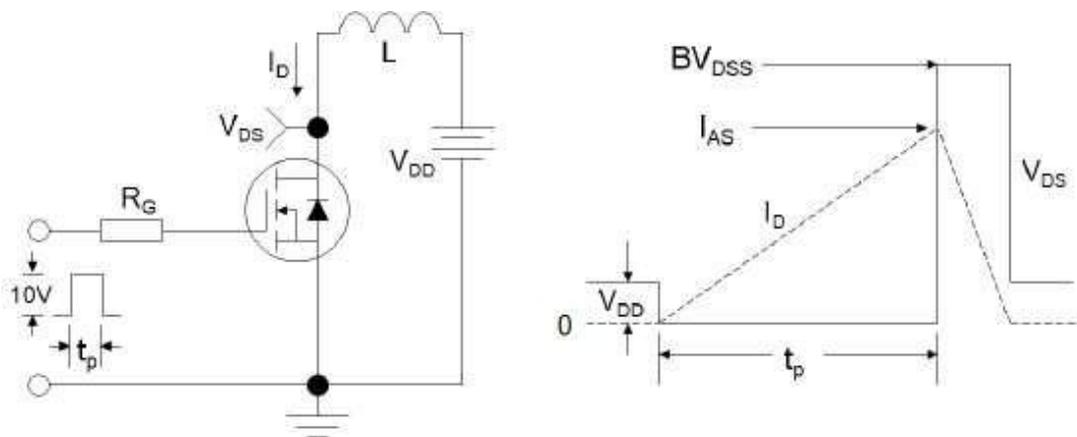
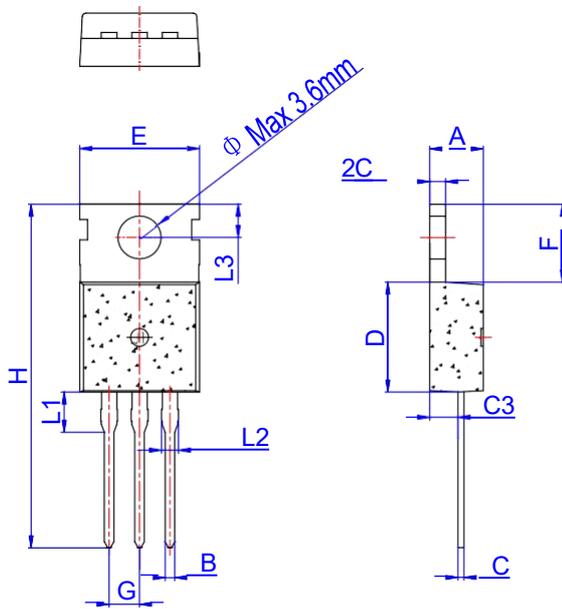


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

## Package Mechanical Data- TO-220C



TO-220C

| Ref.   | Dimensions  |      |      |        |       |       |
|--------|-------------|------|------|--------|-------|-------|
|        | Millimeters |      |      | Inches |       |       |
|        | Min.        | Typ. | Max. | Min.   | Typ.  | Max.  |
| A      | 4.40        |      | 4.60 | 0.173  |       | 0.181 |
| B      | 0.70        |      | 0.90 | 0.028  |       | 0.035 |
| C      | 0.45        |      | 0.60 | 0.018  |       | 0.024 |
| C2     | 1.23        |      | 1.32 | 0.048  |       | 0.052 |
| C3     | 2.20        |      | 2.60 | 0.087  |       | 0.102 |
| D      | 8.90        |      | 9.90 | 0.350  |       | 0.390 |
| E      | 9.90        |      | 10.3 | 0.390  |       | 0.406 |
| F      | 6.30        |      | 6.90 | 0.248  |       | 0.272 |
| G      |             | 2.54 |      |        | 0.1   |       |
| H      | 28.0        |      | 29.8 | 1.102  |       | 1.173 |
| L1     |             | 3.39 |      |        | 0.133 |       |
| L2     | 1.14        |      | 1.70 | 0.045  |       | 0.067 |
| L3     | 2.65        |      | 2.95 | 0.104  |       | 0.116 |
| $\Phi$ |             | 3.6  |      |        | 0.142 |       |